# 2009 1st Asia Symposium on Quality Electronic Design

(ASQED 2009)

Kuala Lumpur, Malaysia 15 – 16 July 2009



IEEE Catalog Number: CHISBN: 978

CFP0983H-PRT 978-1-4244-4951-4

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IEEE Catalog Number: CFP0983H-PRT ISBN 13: 978-1-4244-4951-4

Library of Congress No.: 2009906264

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